

Filename: PMP7167 REV_A_bom.xls

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PMP7167 REV_A BOM

COUNT	RefDes	Value	Description	Size	Part Number	Mfr
1	C3	47uF	Capacitor, Alum Electrolytic 450 V, ±20%	16 x 25 mm	EKXJ451ESS470ML25S	Nippon Chemi-Con
1	C4	0.01uF	Capacitor, Ceramic, 250V, C0G, 10%	1206	Std	Std
1	C7	47uF	Capacitor, Aluminum Electrolytic, 25V	0.200 * 0.435 inch	25V ZL 47uF 5 X 11	Rubycon
1	C10	120pF	Capacitor, Ceramic, Low Inductance, vvV, [temp], [tol]	0603	Std	Std
1	C11	100p	Capacitor, Ceramic, Low Inductance, vvV, [temp], [tol]	0603	C1608X7R1H101K	muRata
1	C12	2200pF	CAP, CERM DISC Y1, 250Vac, 20%	.500 X .310	Std	Std
1	C13	1uF	Capacitor, Ceramic, 50V, X7R	1206	GCM31MR71H105KA55	muRata
1	C100	47pF	Capacitor, Ceramic Chip, 1KV, ±10%	1206	Std	Std
2	C1-2	0.1 uF	Capacitor, Film, 250VAC, 20%	0.689 x 0.217	Std	Std
1	C101	100nF	Capacitor, Ceramic, Low Inductance, vvV, [temp], [tol]	0603	Std	Std
2	C5-6	470uF	Capacitor, multi pattern, SM 1210 to E case + F THole	0.492 inch	EKZM500ESS471MK20S	Nippon Chemi-Con
2	C8-9	0.1uF	Capacitor, Ceramic, Low Inductance, vvV, [temp], [tol]	0603	C1608X7R1H104K	muRata
1	D1	US1K	Diode, Rectifier, 1A, 800V	SMA	US1K	Diodes
1	D2	KBU4J	Diode, Bridge Rectifier, 4A, 600V	KBU	KBU4J	Vishay
1	D3	UHB10FT	Diode, Ultrafast D2PAK, 10-A, 300-V	D2PAK	UHB10FT	Vishay
1	D4	MMSD914	Diode, Switching, 100-V, 200-mA, 225-mW	SOD-123	MMSD914T1	On Semi
1	D5	18V	Diode, Zener, 18V	SMA	1SMA5931BT3	ON Semi
1	D6	MBR0520L	Diode, Schottky, 0.5A, 20V	SOD-123	MBR0520L	Fairchild
1	F1	4A	Fuse, 383 Series, 4A, 300V	0.335	3831400000	Littlefuse
1	L1	10 mH	Inductor, Common Mode , 0.7A	12.5x18 mm	049.67	Kaschke
1	L2	2.2uH	Inductor, Power, 5A, 12 milli-Ohms	0.350 x 0.300 inch	RFB0807-2R2L	Coilcraft
1	Q1	SPD04N80	MOSFET, N-ch, 800-V	D-PAK	SPD04N80C3	Infineon
1	R1	100k	Resistor, Chip, 1-W, 5%	2512	Std	Std
1	R2	1M	Resistor, Chip, 1-W, 5%	2512	Std	Std
1	R4	169K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R6	56.2K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R7	27.4K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R8	71.5K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R9	2.21K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R10	1K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R11	31.3K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R12	20K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R13	100K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R14	3.01K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R15	Open	Resistor, Chip, 1/10W, 5%	0805	Open	n/a
1	R100	100	Resistor, Chip, 0.6W, 1%	2010	Std	Std

1	R101	82k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R3 R5	10	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	T1	82 uH	Transformer, Flyback 50W, ±10%	104.x1358 inch	PH9181NL	Pulse
1	TP4	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
3	TP1-3	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
1	U1	UCC28610D	IC, Flyback Green-Mode Controller	SO8	UCC28610D	TI
1	U2	H11A817A	IC, Photocoupler	MF4	H11A817A	Fairchild
1	U3	TL431AIDBZ	IC, Precision Adjustable Shunt Regulator	SOT23-3	TL431AIDBZ	TI

- Notes:
1. These assemblies are ESD sensitive, ESD precautions shall be observed.
 2. These assemblies must be clean and free from flux and all contaminants.
Use of no clean flux is not acceptable.
 3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
 4. Ref designators marked with an asterisk (***) cannot be substituted.
All other components can be substituted with equivalent MFG's components.

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